

Report NO.: MG00001000042

**1. Product information**

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJP150SN10
Package Type :	TO-220-3L-C

**2. MATERIAL ANALYSIS DATA SHEET**

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.08%
Lead Frame	Iron	7439-89-6	0.15%	65.80%
	Phosphorus	7723-14-0	0.05%	
	Copper	7440-50-8	99.80%	
Soft Solder	Lead	7439-92-1	92.50%	0.33%
	Tin	7440-31-5	5.00%	
	Silver	7440-22-4	2.50%	
Wire1	Aluminium	7429-90-5	100.00%	1.03%
Wire2	Copper	7440-50-8	96.55%	0.25%
	Palladium	7440/5/3	3.10%	
	Gold	7440-57-5	0.35%	
Mold Compound	Silica	60676-86-0	70-82%	32.17%
	Epoxy Resin	29690-82-2	5%-15%	
	Phenol Resin	Trade secret	5%-10%	
	Fire Retardant	Trade secret	0%-5%	
	Carbon black	1333-86-4	0.1%-1%	
Plating	Tin	7440-31-5	100.00%	0.35%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.